X-Celeprint Limited, Lee Maltings, Dyke Parade, Cork, T12R5CP, Ireland

PRESS RELEASE

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Intel has signed a Letter of Intent with X-Celeprint for micro-transfer printing.

Intel and X-Celeprint will explore opportunities to leverage this leading technology platform in connection with **Intel's silicon photonics manufacturing at its New Mexico site**.

X-Celeprint is the world leader in the application of micro transfer print technology, enabling wafer-scale super-heterogeneous integration of diverse materials on a variety of substrates. X-Celeprint's micro-transfer printing enables more efficient and cost-effective use of III-V and II-VI materials while also providing increased production capability. Chiplets of components and material can be transferred individually or as an array from a source wafer in one print step (or to multiple target wafers as required by the end-user application).

About X-Celeprint

X-Celeprint is headquartered at the Tyndall Institute in Ireland leveraging Tyndall's on-site cleanroom facilities and heterogenous integration research expertise. X-Celeprint's R&D team leads MTP research and provides MTP customer industrialisation support and print services both at Tyndall and at the company's North American HQ in North Carolina.

Heterogeneous Integration Starts Here | X-Celeprint